

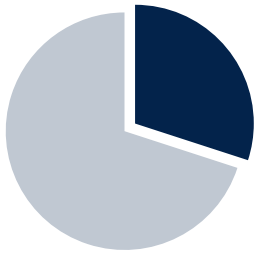


**Capital
Markets
Day 2022**

Microcontrollers & Digital ICs Group

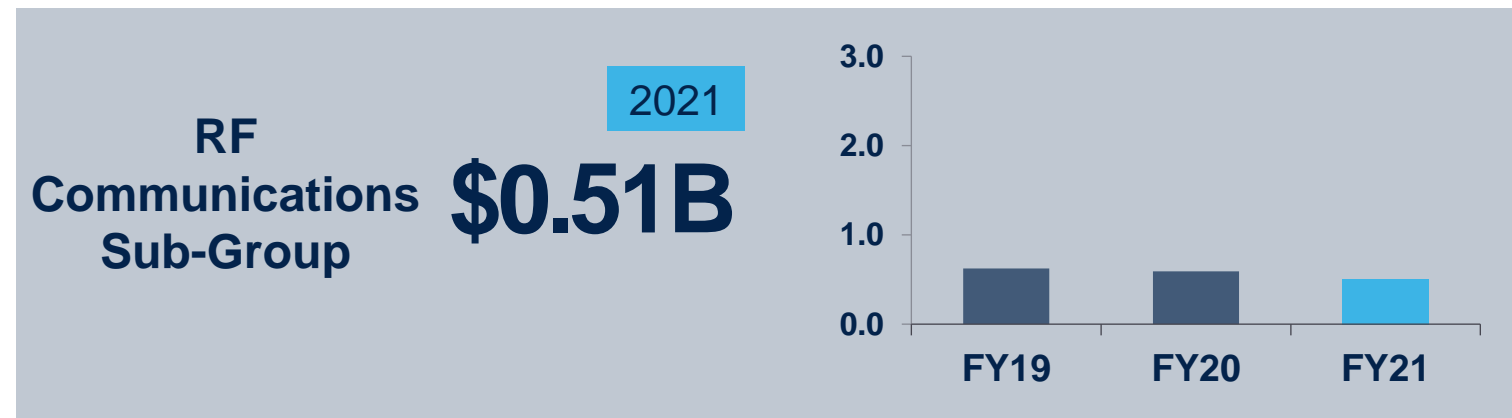
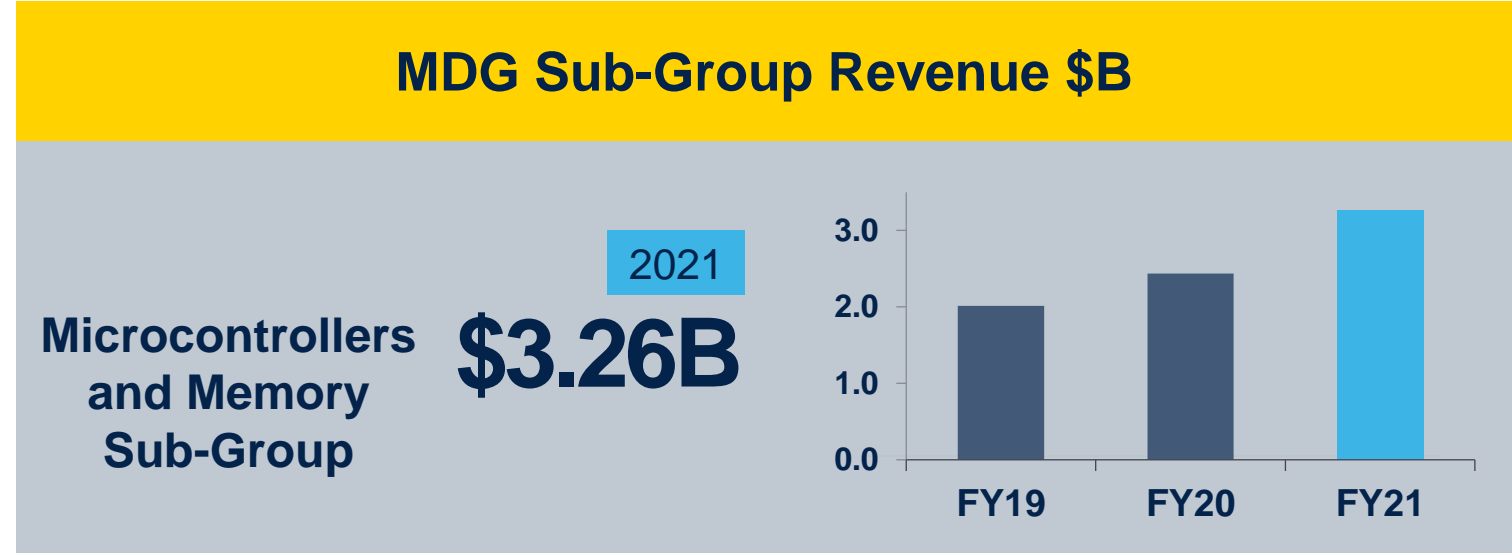
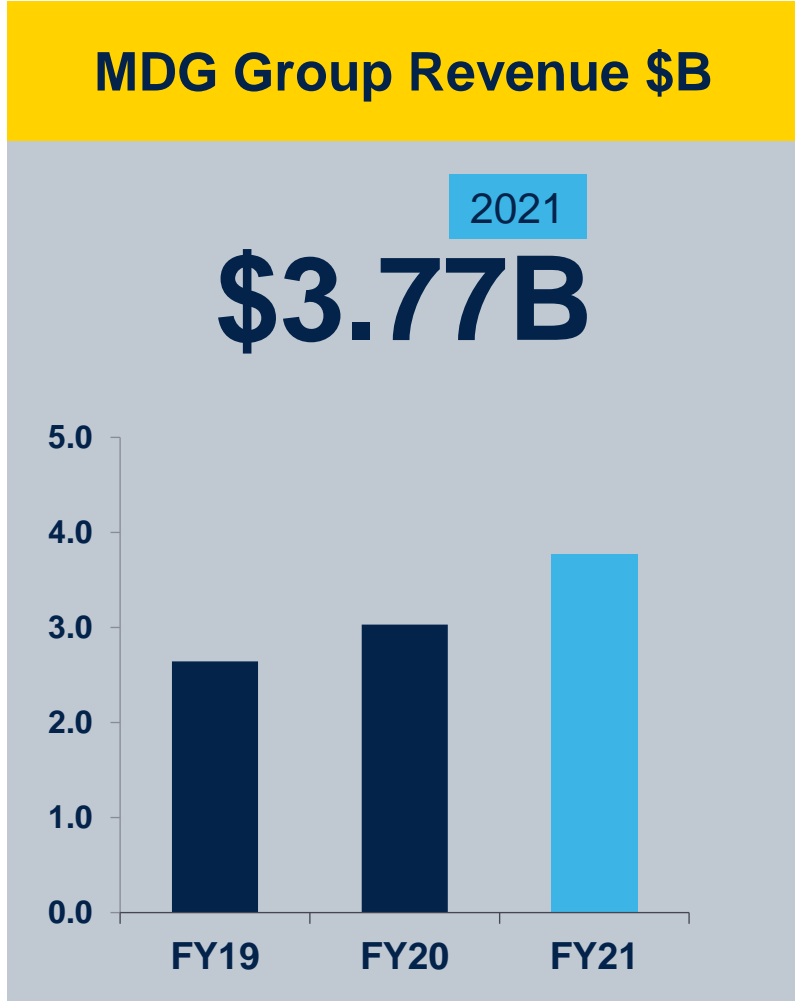
Remi El-Ouazzane

President, Microcontrollers & Digital ICs Group



30% of ST FY21 Revenues

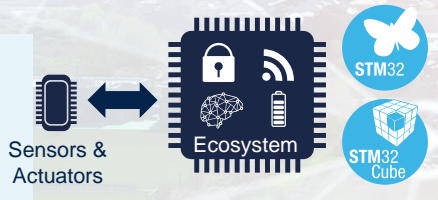
Revenue overview - MDG



Era of the cloud-connected intelligent edge

From: Internet of Things
To: Cloud-connected, Autonomous Things

Our Goal:
Making these Things more **Secure**, more **Connected**, and more **Intelligent**



STM32 | STM32Cube

The edge computing platform of Autonomous Things



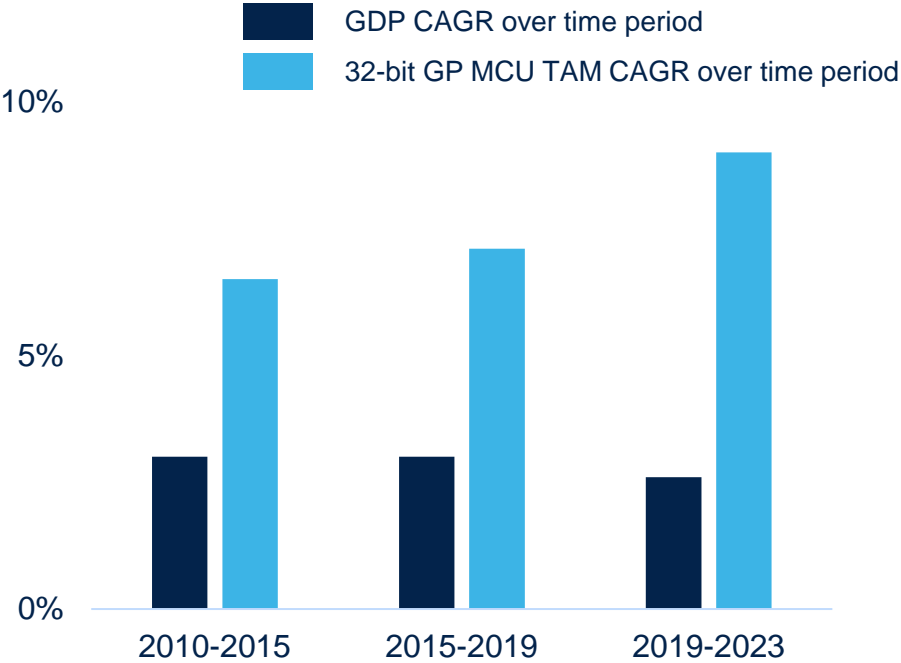
GHz Wireless Infrastructure and Edge RF Front-Ends
To efficiently connect Autonomous Things to and from the Cloud

STM32



32-bit GP MCU: Accelerating the world's digitalization

Digitalization + Cloud-Connection = Increasingly faster growth of 32-bit GP MCU market versus GDP



Growing pervasion of 32-bit GP MCU
Robot mower: from 4 in 2013 to 12 in 2019
Industrial circuit breaker: from 0 in 2012 to 2 in 2022
Power tools: 1 in 2015 to 3 in 2022
Drones: from 1 in 2014 to 7 in 2018

2013

€ 3,400

Main control, HMI
 Motor control
 Obstacle detection
 Sensor control

1x STM32, 1x STM32, 1x STM32, 1x STM32

2019

€ 5,000

Advanced User Interface
 Main control
 2x Motor control
 Obstacle detection
 7x Sensor control

1x STM32, 1x STM32, 1x STM32, 1x STM32, 1x STM32, 1x STM32, 1x STM32, 1x STM32

Husqvarna



STM32: the leading 32-bit MCU for Industrial

ST market share: 23% - #1
of 2021 General Purpose MCU* TAM

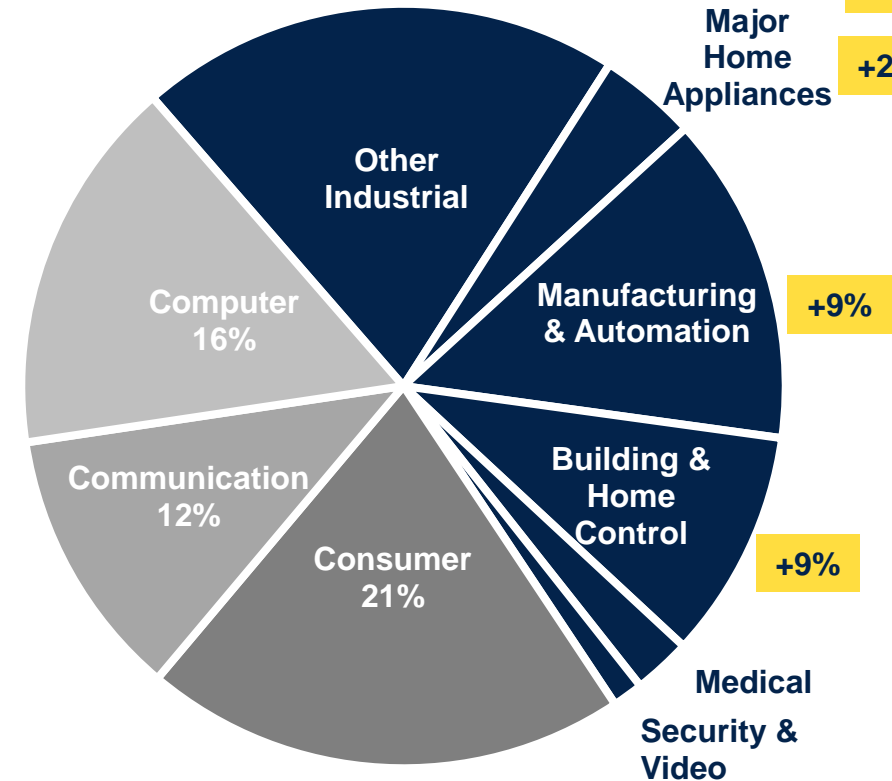
2017	2018-2020	2021
	Competitor A	#1
B	#2	A
#3	Competitor B	

Organic growth driving ST market share gains

2021-2026 Industrial market growth drivers

- Home appliances - Energy efficiency & cloudification
- Factory automation - AI based predictive maintenance
- Power tools - Wireless connectivity
- Automotive electrification - Infrastructure development
- Building - Smarter, safer and more energy efficient

2021 32-bit GP MCU* TAM(\$M)



Industrial growing from 52% of TAM in 2021 to 65% in 2026



Developer-first strategy: STM32Cube



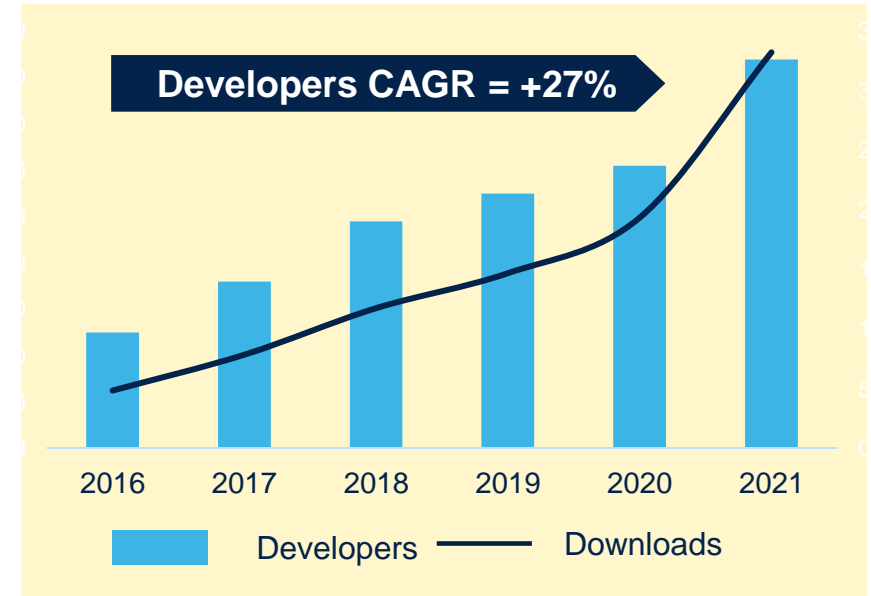
Applicative Reference Implementations

Extension Libraries and AI toolkit



2M* Unique Developers	2M* HDK shipped	8M* SDK & tool kits Downloads	10k/y X-Cube.AI Downloads
> 120 HDK references	> 150 Cube Expansions	> 150 MOOC hours	> 100 Partners

* Cumulative over 5 years



Next growth drivers for the STM32

1 Increase existing GP MCU socket value with Security, Wireless Connectivity, AI, and ST adjacencies (Analog, MEMS, Power)

2 Capture new higher value MPU sockets

Capitalize on our 100,000+ STM32 customer base



1



Democratizing Edge to Cloud Security

Building turn-key secure solutions for IoT nodes

Scalable Security

 STM32   SESIP psacertified™ Level 3	 STSAFE-A110  COMMON CRITERIA Level 5+
--	---

Highest security certifications

MCU only or MCU+Secure Element

Certified by major Cloud vendors


Ready for IoT
STM32U5 / STSAFE-A110



Discovery kit for IoT nodes with STM32U5



From portable device



Milwaukee Tools Battery

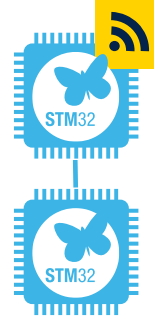
To Highly Secure



SpaceX-StarLink Router & antenna

1

The Cloudification of the STM32 customer base



Wireless Connectivity growth drivers

- Network Effect
- Cloud connectivity for new use cases
- Diversity of wireless technologies



Connecting 100 000+ STM32 customers

Broadest wireless protocol offering



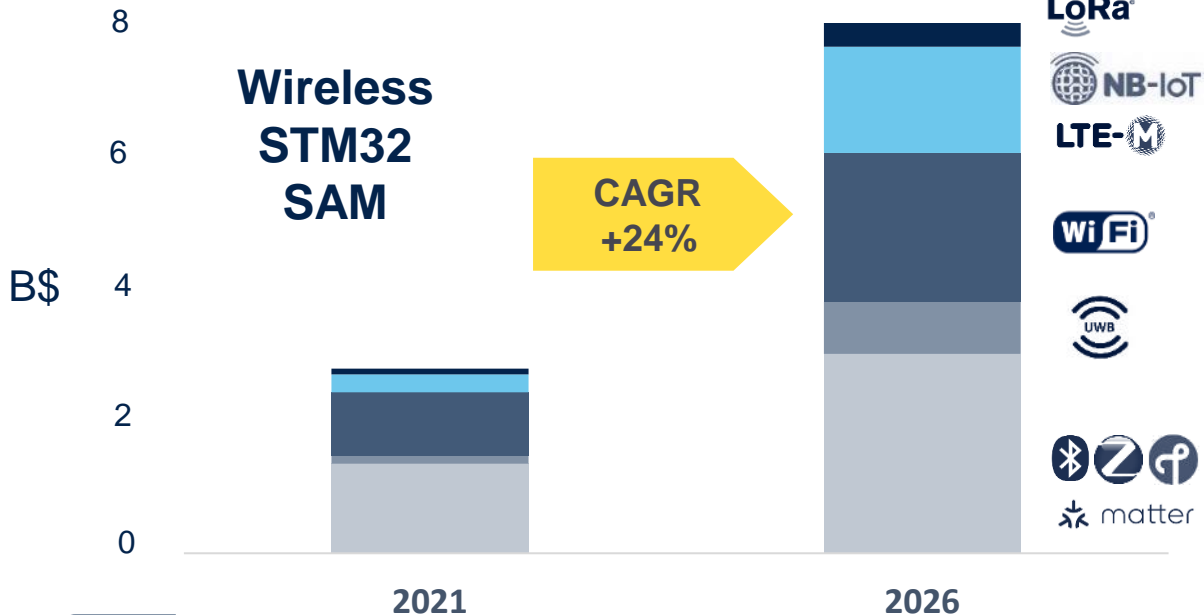
Seamless Software migration



Built-in Security



Cloud Native



Source: ABI

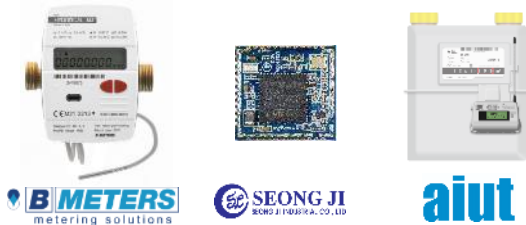
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Accelerating momentum in wireless connectivity

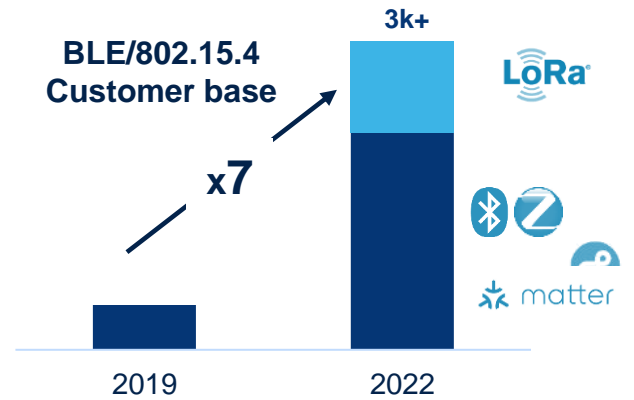
Seamless Software Migration STM32Cube is the Foundation



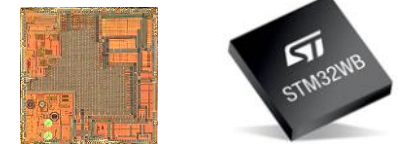
Broad range of Industrial Wins



Building customer trust >\$100M*, 42% Industrial



**World 1st true open dual-core
BLE/802.15.4/Matter MCU**



- *ST 2022 forecast
- 1st time >\$100M of BLE/802.15.4 revenue
 - Industrial applications estimate as % of revenues

1

Making AI at the edge a reality

Introducing ST's game-changing Neural MCU



STM32N6

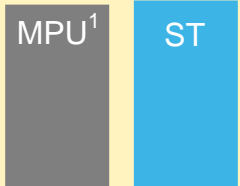
First MCU with **ST Neural-ART NPU Accelerator**

State of the art Inference/W and Inference/\$

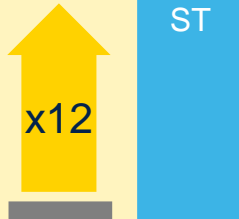
Powered by



Performance
Inference/s



Energy Efficiency
Inference/W



Value for money
Inference/\$



"The new STM32N6 Neural MCU is dramatically lowering the AI technology implementation price point. This breakthrough supports our roadmap of new generation intelligent sensors allowing rapidly growing adoption in Smart Cities"



Vincent SABOT,
Executive Managing Director, LACROIX - City activity



¹ Comparison with competitor quad-core microprocessor with AI hardware acceleration

Accelerating Development of Edge AI Solutions

CARTESIAM Edge AI Productivity Lab

- No AI experts required
- Up to 95% shorter development cycle
- Fit small footprints, MCU & ISPU
- Accretive royalty model



Anomaly detection sensor



- STM32F4**
- 12 months from concept to market
 - Multi sensor capability
 - Extreme flexibility
 - Broad deployment planned

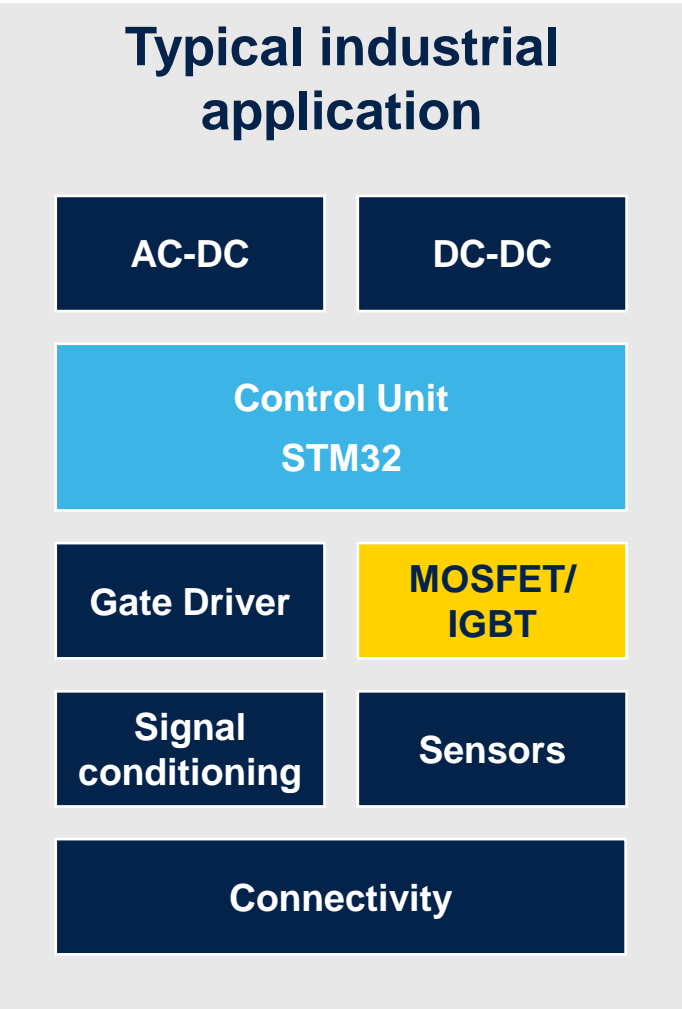
Predictive maintenance



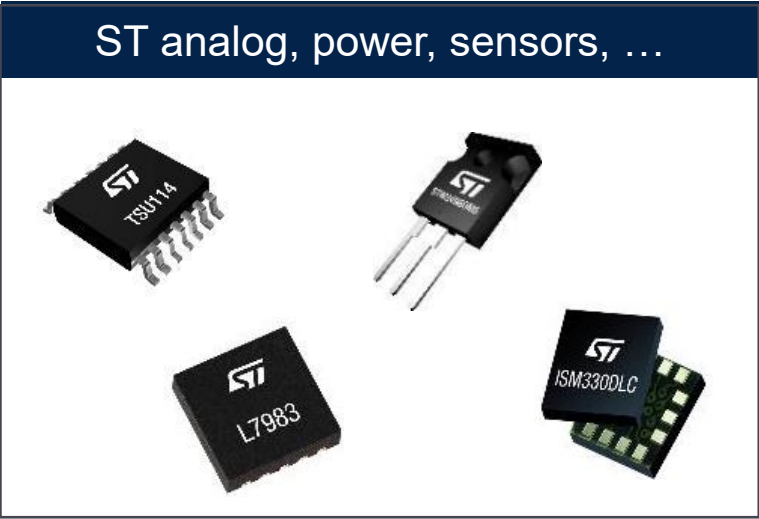
- STM32F4**
- 30% increase in cutting tool life
 - Preventing operational failure
 - Extending to all drilling & cutting tools

1

Maximizing ST attach rate in industrial applications



+



Driving ST Growth

STM32	Attach
\$17.1	\$131
	x8

STM32	Attach
\$8.8	\$16.9
	x2

STM32	Attach
\$1.8	\$6.2
	x3

STM32	Attach
\$2.4	\$12.4
	x5

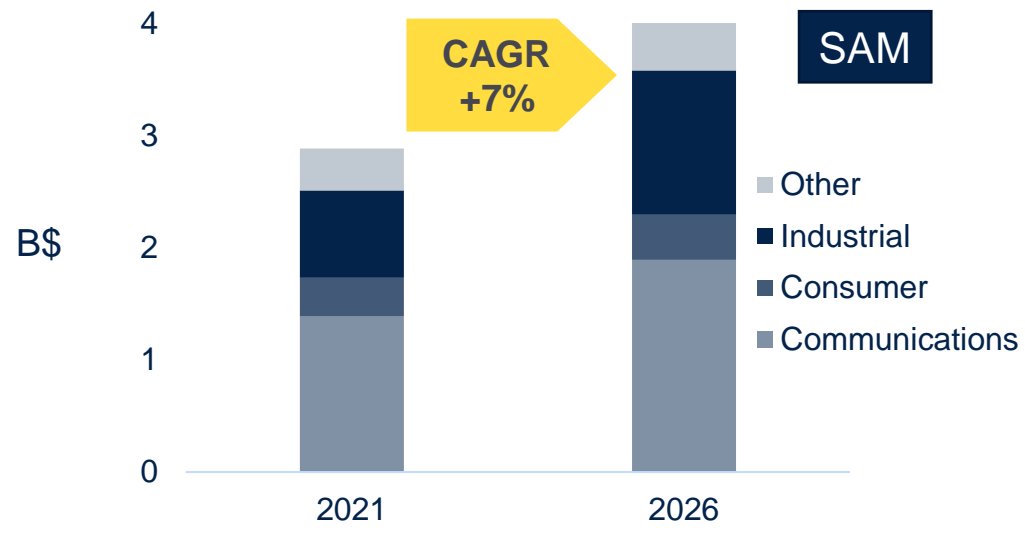
Actual implementation based on selected customer products

2

STM32 MPU: Building on STM32 industrial success



The natural evolution of STM32 MCU portfolio



Expanding our 100K+ MCU customer base in embedded processing



Differentiate in Open Source Software
 OpenSTLinux = Reference 32-bit platform in OSS community



Leverage STM32Cube
 Full re-use of selection, configuration and development tools of the STM32 MCUs
 Natural continuity for our 100 000+ MCU customers

STM32MP: General purpose MPUs for the Industrial Market

2

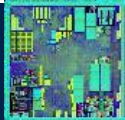


Power management IC for STM32 MPUs

24 STM32MP1 product lines

STM32MP15x

- Single and dual A7 core
- Real Time domain with Cortex M4
- Industrial interfaces (Ethernet, CAN,..)
- GPU + display interfaces



STM32MP13x

- Single A7 core
- Dual Ethernet
- Sub \$3
- PCI security
- Ramping soon at OEMs



"We are adopting ST's new STM32MP135 because it offers the perfect cost/performance balance while meeting the strong security requirements of our next generation product family"

World leader in payment services

150+ Customers
10M+ units*
3x YoY growth since 2020

Smart home & building

Point-of-Sales

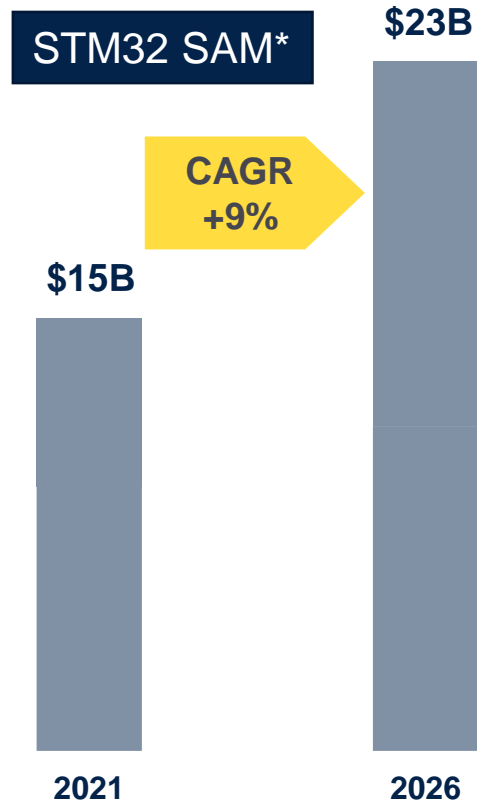
SOM** makers

Factory Automation

Digital power & energy management



Growing STM32 revenue faster than the SAM



*GP MCU + Wireless MCU + Embedded-MPU

1

GP MCU revenue to grow in line with SAM in units and more than SAM in \$, leveraging added value

1

Wireless MCU revenue to grow faster than SAM thanks to portfolio expansion, customer base & ease of SW migration

2

Double digit **MPU revenue** growth - growing faster than SAM thanks to enriched and accelerated product line introductions

Source: WSTS, ABI, ST

GHz Wireless



life.augmented

Addressing GHz wireless growth opportunities with RF

RF Front-Ends (LPPD, PA, LNA, SW, Filters) & Beamformer

Infrastructure



Edge*



*excluding Smartphone

Diverse business models

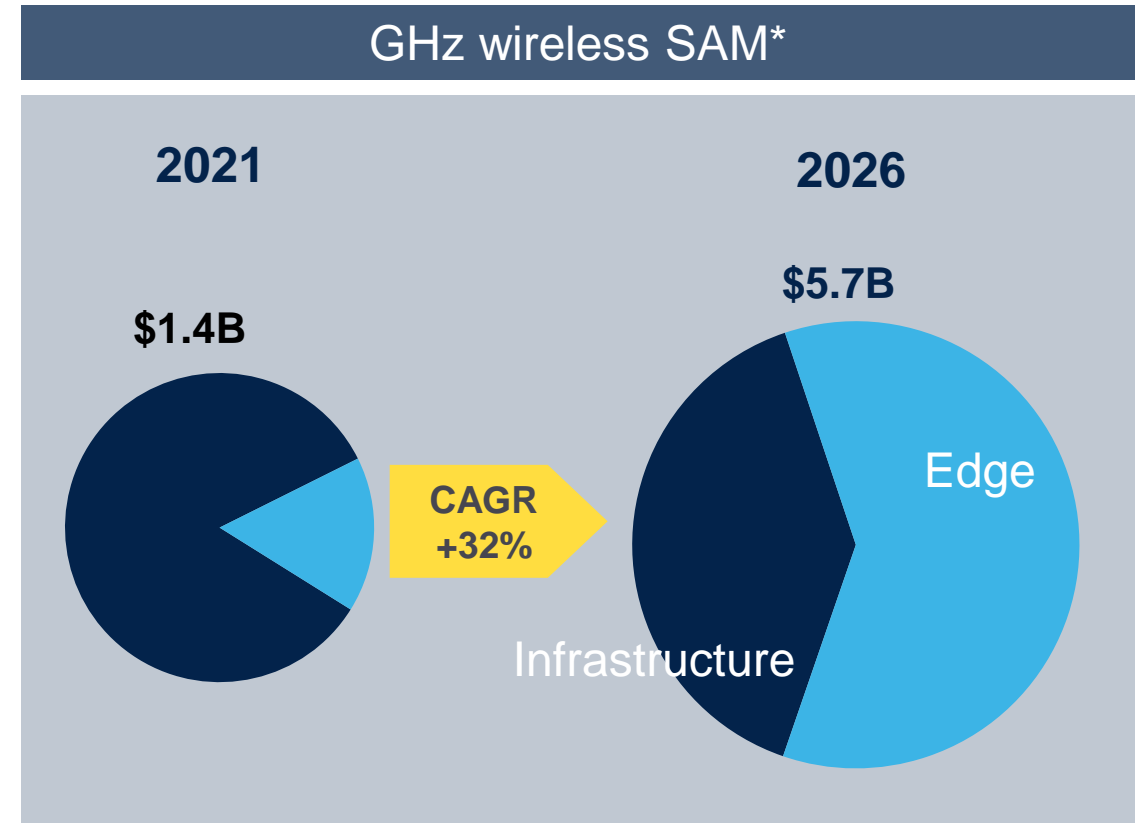
	ASSP	CSSP	ASIC	COT
System & Product specification	ST	Customer	Customer	Customer
RF, analog & digital design		ST		
IP & Physical Implementation			ST	
Wafer manufacturing				ST
Packaging, test & supply-chain			ST	

Fast growing GHz wireless market



GHz Wireless growth drivers

- **LEO satellite communication** gaining traction as an alternative for broadband internet access
- **5G mMIMO** deployment globally
- **Wi-Fi 6 & Cellular-IoT** growing fast



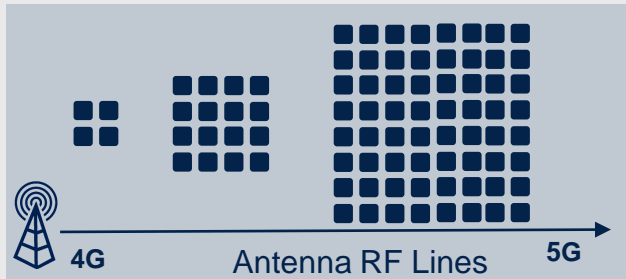
Source: ST

*SAM

- Infrastructure: RF Front-End & Beamformer for 5G BTS mMIMO, mmWave & Small Cells, LEO Satellites
- Edge: RF Front-End & Beamformer for LEO Satellite User Terminals, C-IoT, Wi-Fi 6 (excl. Smartphones)

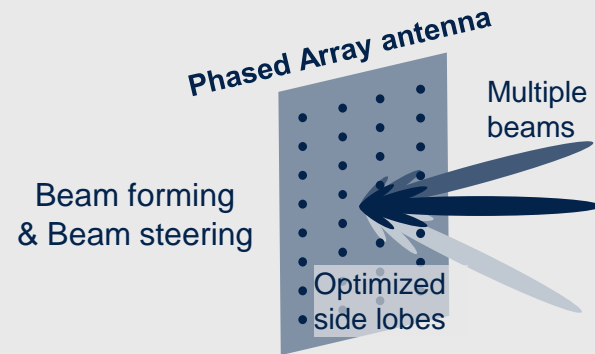
Key technology drivers of the GHz wireless market

Multiplication of RF chains



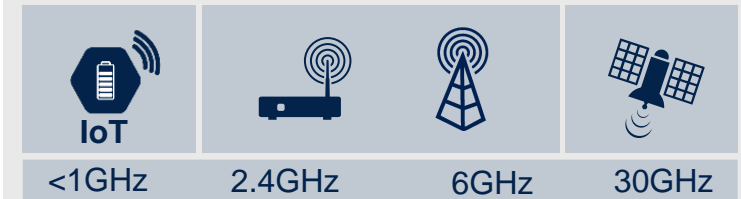
- Driven by **Massive MIMO & Phase Array Antenna**
- **Number of RF chains dramatically increases** from traditional Base Station

Adapting key RF FE KPIs



- Fundamental importance of **Noise Figure** for receiver sensitivity
- New transmitted peak power paradigm allows **highest power efficiency**

Wide frequency span



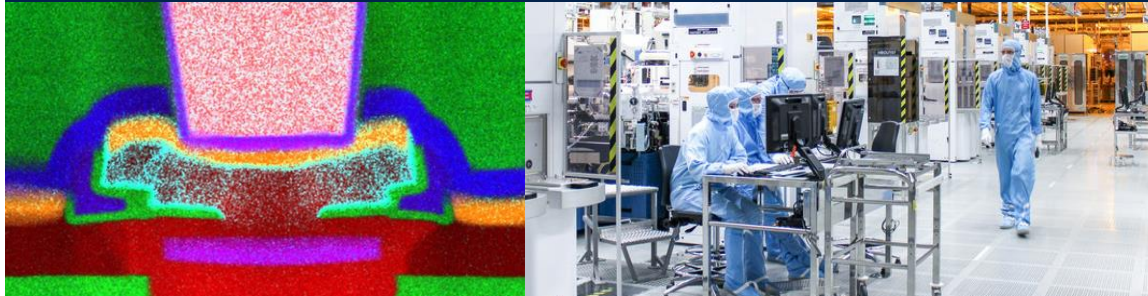
- **Higher throughput** calls for more bandwidth,
- **Available bands** are many & broadly scattered
- From **SubGHz to mmWave**

This requires **new core technologies** optimized for these new targets and **consumer-like volume**

Building GHz wireless products on ST technology leadership

BiCMOS

200mm wafers for high-volume 130nm SiGe (B9MW)
300mm wafers for leading-edge 55nm SiGe (B55X)



- **LNA_{20GHz} NF** -0.2dB (B55X vs best available foundry)
- **LNA_{20GHz} Gain** +6dB (B55X vs best available foundry)
- **F_{max}*F_t** x1.9 (B55X vs best available foundry)

Major B55X product tape out in H2'22

Best Noise Figure (NF) on the market for beamformers



“ST's BiCMOS technology benefits in term of Noise Figure performance proved fundamental for SpaceX system performance.”

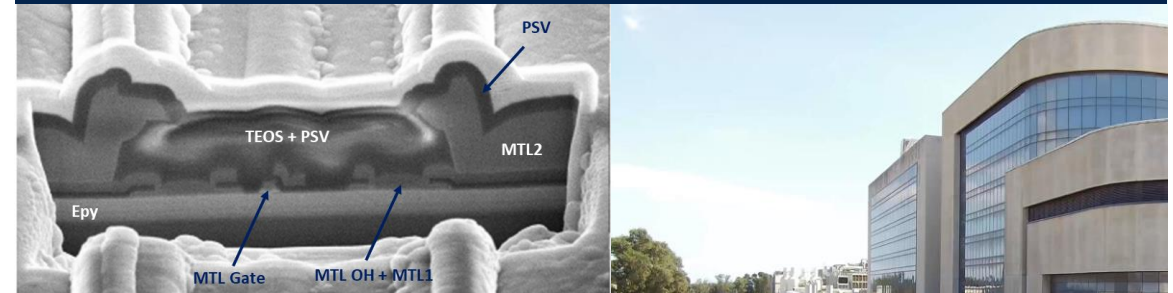
Mark Juncosa, SpaceX VP of Engineering



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GaN-on-Si

Cost-effective GaN for RF volume markets
150mm – 200mm CMOS-like manufacturing



- **Power Density** x5 vs LDMOS* (on par with best available GaN)
- **Drain Efficiency** >75% (on par with best available GaN)
- **PA Efficiency** +10% vs LDMOS

Qualification in progress

Optimal solution for 5G mMIMO PA



“GaN-on-Silicon is a highly competitive technology versus LDMOS and GaN-on-SiC in key markets and its near-term availability makes it an attractive choice.”

Steve Daly, Macom CEO

* Lateral Drain Extended Metal Oxide Semiconductor

ST products for GHz wireless market



Sampling now **NEW**

FE Ku Band CSSP
12-15GHz

2023

- ➔ Increase frequency to Ka band
- ➔ Porting to B55X for even better NF
- ➔ Cost-down through 300mm volume

Best NF
Best sensitivity
High-volume



NEW **NEW**

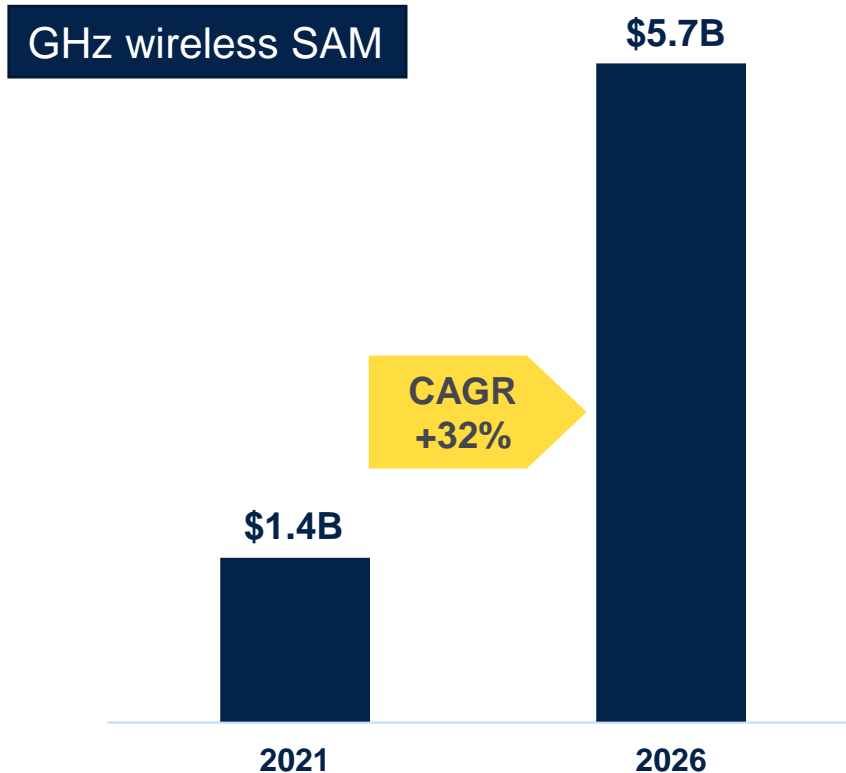
STFETxx LPPD
1.8-5GHz

GAN PAM
3.4-3.8GHz

- ➔ Portfolio extension to new bands / power
- ➔ Complete integration in a SIP
- ➔ Cost-down with 200mm GaN-on-Si volume

Perfect technologies to cover the full Tx line-up
Right cost & Power
Added Efficiency (PAE)

Growing revenue faster than the GHz wireless market



Leverage **ST technology leadership** in core technologies: BiCMOS & GaN-On-Si, Beamformers, Front-End modules
Volume-ready packaging & test

Capitalize on leadership for **LEO Satellite Communication**
- 500M ICs delivered to date

Expand in **5G mMIMO and mmW** with breakthrough GaN-on-Si PA technology
- Sampling lead customer in H2 2022

Expand engagements on **Cellular-IOT and Wi-Fi 6 FEMs & RF switches**
- Multiple engagements currently ongoing

Source: ST

Supporting ST \$20B+ revenue ambition

Two strong pillars of growth

STM32 and GHz Wireless RF Front-End & Beamformer

STM32: Leveraging our established customer base and STM32Cube ecosystem to expand the SAM of the franchise

GHz Wireless: leveraging ST technology innovation and leadership to build new product lines in fast growing markets

Strong potential for **incremental revenue** over next 5 years, accretive to company operating margin targets



Our technology starts with You



Find out more at www.st.com

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